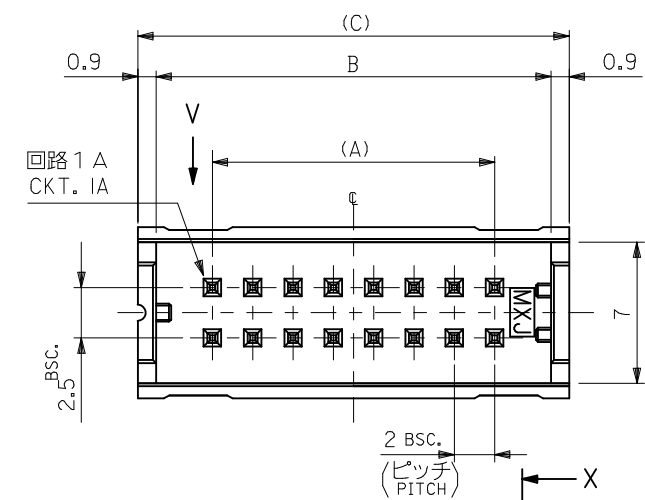
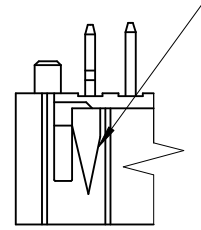
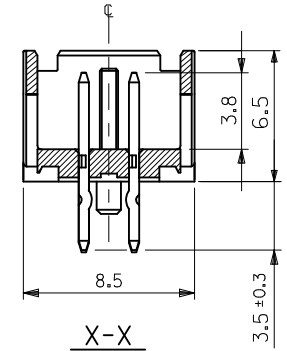
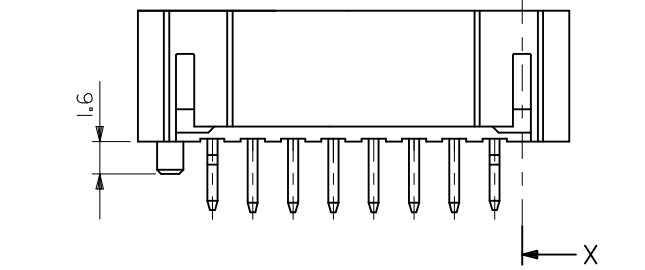




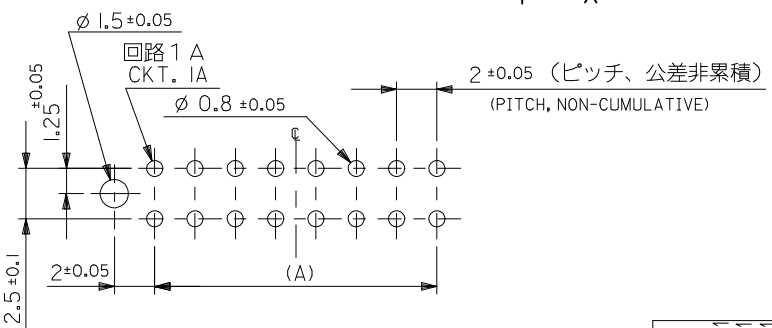
回路 1 A 表示
CKT. 1A IDENTIFICATION



V



X-X



基板取付穴推奨寸法 (参考)
RECOMMENDED PCB HOLE DIM.(REF.)

MATERIAL
材料
注記参照
SEE NOTES

注記
NOTES

1. 材料 :
MATERIALS:
ウエハー : ホリアミド、ガラス充填、UL94V-0、色: グレー
WAFER : PA, GLASS FILLED, UL94V-0, COLOR: GRAY
ピン : 黄銅、スズメッキ
PIN : BRASS, PRE-TINNED
2. 適合メスコネクター : 51089-***5, 52478-***15, 52484-***15
MATING CONNECTOR
適合クリップ : 51094-***00
MATING CLIP
3. 推奨基板厚 :
RECOMMENDED PCB THICKNESS : t
4. メッキ仕様
TERMINAL PLATING
表面メッキ : スズメッキ 1μm MIN.
SURFACE PLATE : TIN 1μm MIN.
下地メッキ : ニッケルメッキ 0.5μm MIN.
UNDER PLATE : NICKEL 0.5μm MIN.
5. ELV AND RoHS COMPLIANT.

無鉛
LEAD FREE

65.4	63.6	58	53313-6065	60
55.4	53.6	48	-5065	50
45.4	43.6	38	-4065	40
39.4	37.6	32	-3465	34
35.4	33.6	28	-3065	30
33.4	31.6	26	-2865	28
31.4	29.6	24	-2665	26
29.4	27.6	22	-2465	24
27.4	25.6	20	-2265	22
25.4	23.6	18	-2065	20
23.4	21.6	16	-1865	18
21.4	19.6	14	-1665	16
19.4	17.6	12	-1465	14
17.4	15.6	10	-1265	12
15.4	13.6	8	-1065	10
13.4	11.6	6	-0865	8
11.4	9.6	4	53313-0665	6
(C)	B	A	TRAY PACKAGE	CKT.
			ORDER NO.	

REVISED
EC NO: J2010-03/49
DRWN:TKN 2009/08/31
CHKD:KASAKAWA 2009/08/31
APPR:NUKITA 2009/08/31
REV B

DESCRIPTION
GENERAL TOLERANCES (UNLESS SPECIFIED)
10 UNDER ±0.2
10 OVER 30 UNDER ±0.25
30 OVER ±0.3
ANGULAR ±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY
DRAWN BY A. IDA DATE 2003/05/07
CHECKED BY J. MIYAZAWA DATE 2003/05/07
APPROVED BY Y. ITO DATE 2003/05/07
MATERIAL NO. SEE CHART
SIZE A3

SCALE
4:1
DESIGN UNITS
METRIC
THIRD ANGLE PROJECTION
TITLE
2.0 W/B DUAL ROW S/T HEADER ASSY
MOLEX INCORPORATED
DOCUMENT NO. SD-53313-002
SHEET NO. 1 OF 1

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